

Abstract

An optical fiber terminator package (300) has a chip with a surface with one or more light emitting devices (314) and at least one photoreceptor (312) formed on or in the surface. A cap (302) is bonded to the surface of the chip to encapsulate the devices (312, 314). The cap (302) has one or more regions (316, 318) transparent to light passing to or from the devices (312, 314). The cap (302) has been bonded to the semiconductor chip at the wafer stage prior to separation of the wafer into individual packages.

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